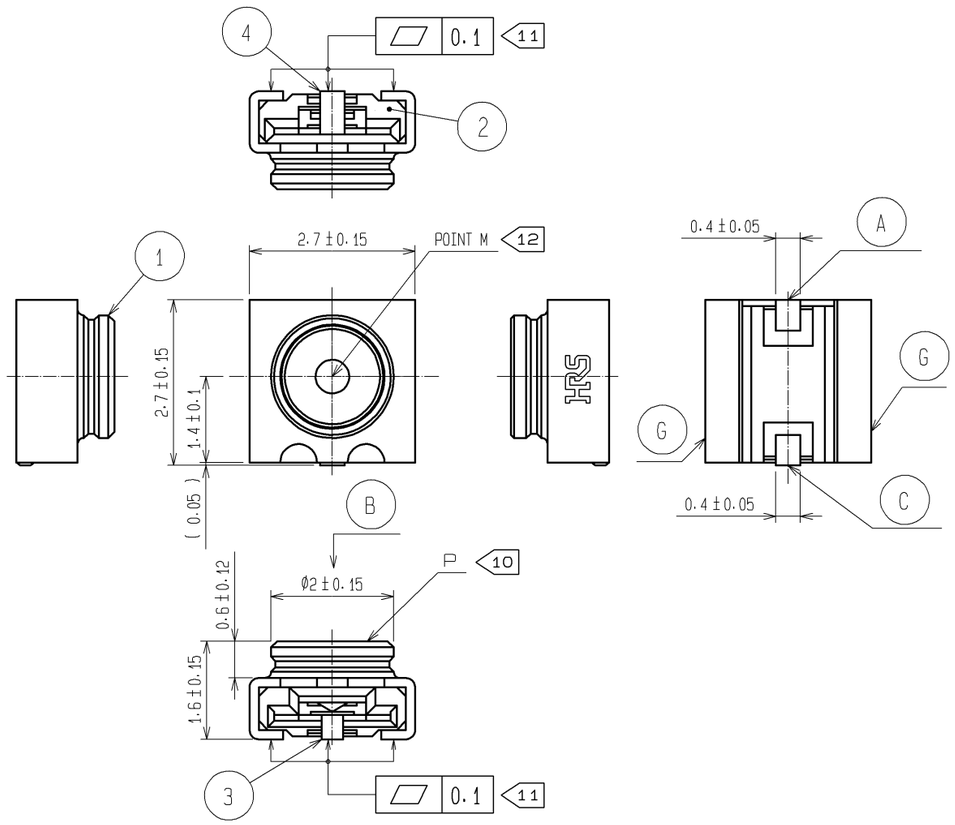


Note 1 Please do not change the specified layout of the PCB dimension and the layout of the stencil plate dimension and thickness otherwise could not be responsible for the solderability of the product.

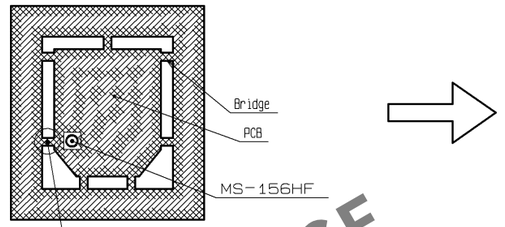
2 When copper-foil and resist are designed on the ▨ area where underneath the product, Hirose can not gurantee the product.

3 Manual soldering could not be accepted on this product to prevent solder wicking and flux penetration.

4 The bridges should be designed with a sufficient distance from MS-156HF to prevent getting the cutting micro chips into the contact area.

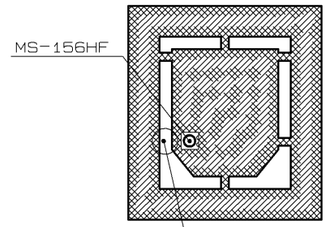
~Example of PCB design~ (Layout of MS-156HF and Bridge)

~No good design~



In this position where the bridge is close to MS-156HF, there is possibility of causing disfunction caused by what the cutting micro chips get into MS-156HF when cutting PCB.

~Recommended design~



The cut position should be designed with a sufficient distance from MS-156HF.

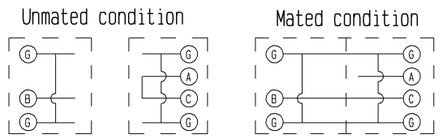
5 Do not use this product as an interface, this product is only for circuit inspection.

6 Please refrain from using the product in environments specifically affected by excessive vibration, shock, dust, high humidity, gases, very high temperatures and very low temperatures such as outdoor equipment. It might cause degradation or destruction of the product. Even if it endures during a short time, long time quarification is not guaranteed.

7 Plugs can be roughly classified to two types.
- For mass production line automatic check (Press down type)
- For manual check (With retentive lock) : Unable to be used at production line.

8 Do not use a washing process.

9 Circuit shall be as follows.



10 For use of this product, be sure to put contact area of plug on position P perpendicularly.

11 Lead coplanarity is to be 0.1mm MAX.

12 Point M indicates the center of the mating portion.

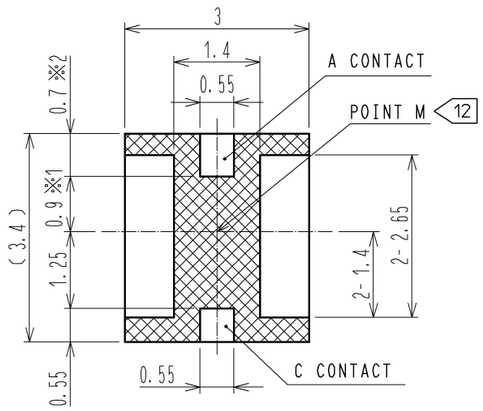
△1 13 All lead layout is the same as MS-156NB which is conventional product, therefore the specified mounting condition of MS-156NB which shows dimension correspond to each ※ number of the following is also available.

	※1	※2	※3	※4
size	1.05	0.55	1.05	0.3

1 SPECIFIED PCB LAYOUT

13 (TOLERANCE ±0.05mm)

There is possibility of a causing disfunction on the condition other than specified.

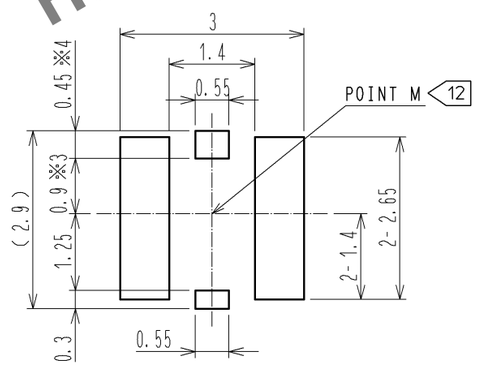


1 SPECIFIED STENCIL PLATE

13 THICKNESS:0.1~0.12mm

(TOLERANCE ±0.03mm)

There is possibility of a causing disfunction on the condition other than specified.



2 ▨ FREE AREA OF COPPER-FOIL AND RESIST

Please comply with the following notes as a request for cooperation to our customers due to the micro precision machinery component. (We ask all our customers for their understanding of the following notes and their cooperation.)

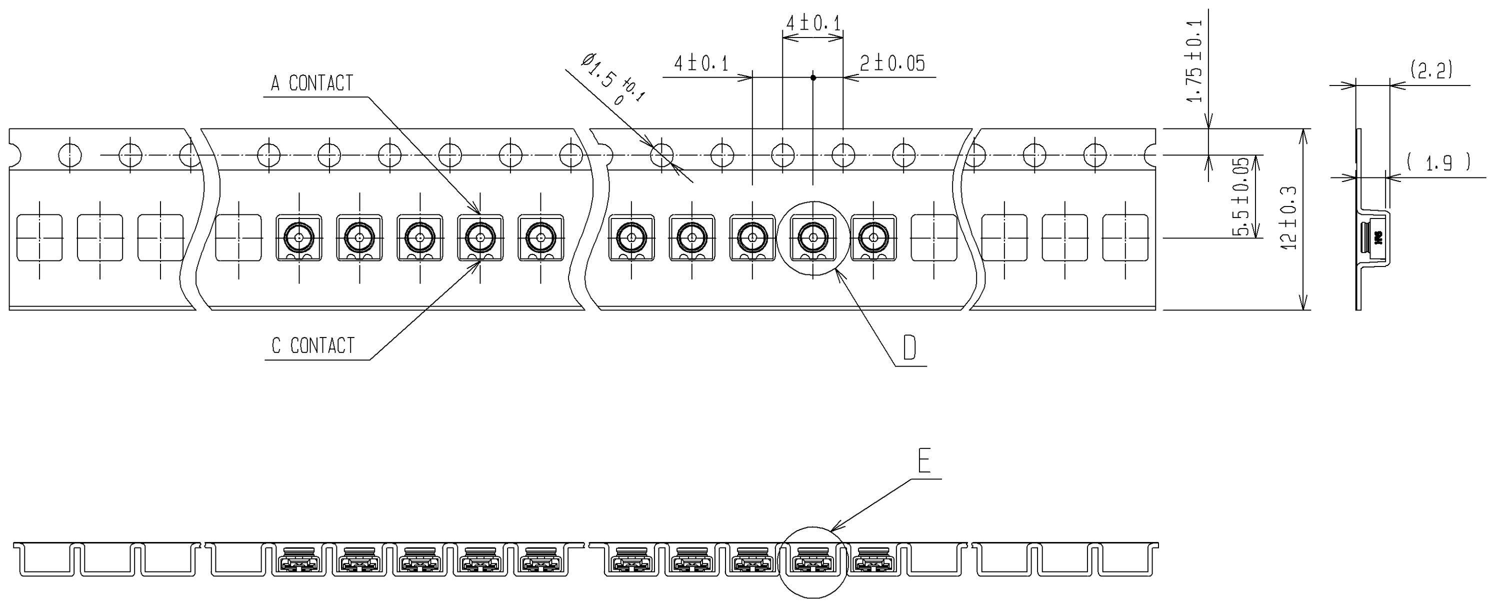
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
3	BERYLLIUM COPPER	SELECTIVE GOLD PLATING	6	PS	
2	6T-NYRON		5	PS	
1	PHOSPHOR BRONZE	GOLD PLATING	4	PHOSPHOR BRONZE	SELECTIVE GOLD PLATING

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10 : 1	△1 1	DIS-J-000833	DS. YAMAKOSHI	TY. OZAKI	08.04.07

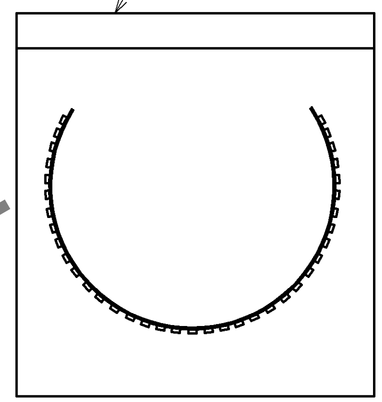
HIROSE ELECTRIC CO., LTD.

APPROVED	KJ. KAWAMURA	08.03.10	DRAWING NO. EDC3-180639-04
CHECED	TY. OZAKI	08.03.10	PART NO. MS-156HF(01)
DESIGNED	DS. YAMAKOSHI	08.03.07	
DRAWN	DS. YAMAKOSHI	08.03.07	CODE NO. CL358-0238-4-01 △1 1/2

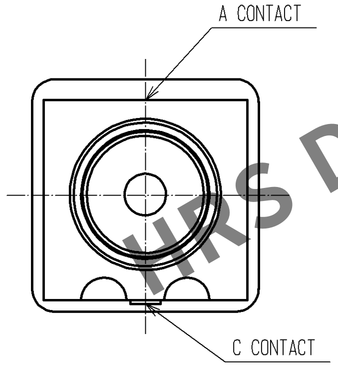
PACKAGING SPECIFICATION



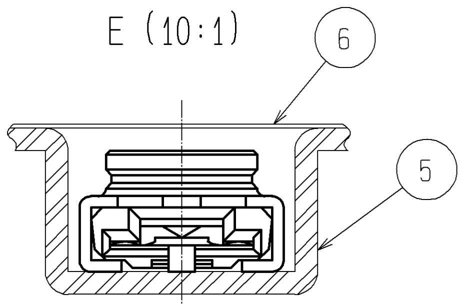
DRAWING OF PACKING
(100PCS PER REEL)



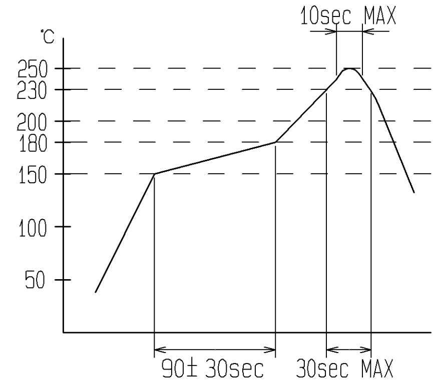
D (10:1)



E (10:1)



RECOMMENDED REFLOW TEMPERATURE PROFILE



FOR LEAD-FREE SOLDER

MAX TEMPERATURE: 240~250℃ 10sec MAX
230℃ OR MORE : 30sec MAX
150~180℃ : 90± 30sec
REFLOW :2 TIMES MAX

DRAWING NO.	EDC3-180639-04	
PART NO.	MS-156HF(01)	
CODE NO.	CL358-0238-4-01	1 2/2